

ABSTRACT OF THE DISCLOSURE

In a method of molding resin to seal electronic parts, an internal die space portion (38) which is defined at least by pots (9), cull portions (25), resin passages (26) and cavities (10, 20) when an upper mold section (1) and a lower mold section (2) are closed is cut off from the exterior to carry out evacuation by a vacuum source (40) and instantaneous evacuation by an instantaneous evacuation mechanism (45). According to this method, it is possible to quickly improve the degree of vacuum in the internal die space portion (38) by efficiently and reliably discharging air, moisture and gas from the internal die space portion (38) to the exterior due to synergistic action of the evacuation and the instantaneous evacuation. Consequently, resin molded members are prevented from formation of voids.

